ONE-STOP SUPPLIER OF SEMICONDUCTOR CARRIER PRODUCTS

Hiner-pack® MHWJ Canister 200 mm

Engineered for safe handling of delicate wafers during shipping and storage

Wafer jars offer a cost-effective multi-wafer storage and transport solution, ideal for non-sensitive wafers. These jars are molded from natural polypropylene and fitted with secure lids to prevent accidental opening. Inside, interleaf separators, foam cushion disks, and liner foam walls form a multi-layer protective environment that isolates wafers from mechanical shock, vibration, and direct surface contact. Available in sizes for 150 mm and 200 mm wafers (customised sizes are available), and in clear, white, or black for inspection or ESD control. The stackable design optimizes cleanroom storage, while the reusable construction reduces packaging waste. From in-fab storage to inter-fab shipping, wafer jars deliver reliable contamination prevention and physical protection for high-value wafers throughout the production cycle.

Manual loading is straightforward, making these jars ideal for non-automated environments. This layered protection system is widely used for cleanroom storage and transport of finished wafers with minimal contamination risk.





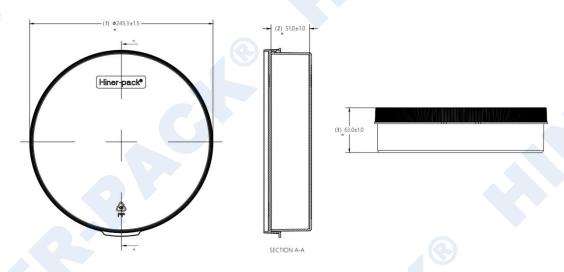
SPECIFICATIONS

- 245.3 mm L × 245.3 mm W × 63 mm H (9.66" × 9.66" × 2.48")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (32)

FEATURES & BENEFITS

- Interleaf separators prevent direct wafer surface contact
- Foam liners and cushion disks absorb shocks and vibration
- · The bottom and the top cover are designed to facilitate the operator to open and ensure safety during transportation

DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MHWJ-8/25-230/50-NP	Bottom+Foam+Interleaf+Liner+Top	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm ³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	23°C ISO 180	6 kg.cm/cm
	-20°C	notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



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